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DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 2002 Nov 18 2004 Mar 29



FEATURES

- Ultra small plastic SMD package
- C4: 2.75 pF; ratio: 2.4
- · Low series resistance.

APPLICATIONS

• Voltage controlled oscillators (VCO).

DESCRIPTION

The BB145B is a planar technology variable capacitance diode in a SOD523 (SC-79) package.

PINNING





ORDERING INFORMATION

TYPE		PACKAGE		
NUMBER	NAME	DESCRIPTION	VERSION	
BB145B	-	plastic surface mounted package; 2 leads	SOD523	

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _R	continuous reverse voltage		-	6	V
V _{RM}	peak reverse voltage	in series with a 10 k Ω resistor	-	8	V
I _F	continuous forward current		-	20	mA
T _{stg}	storage temperature		-55	+150	°C
Tj	operating junction temperature		-55	+150	°C

ELECTRICAL CHARACTERISTICS

 $T_i = 25 \ ^{\circ}C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I _R	reverse current	V _R = 6 V; see Fig.3	-	10	nA
		$V_R = 6 V; T_j = 85 \ ^\circ C; see Fig.3$	-	200	nA
r _s	diode series resistance	$f = 470 \text{ MHz}; \text{ V}_{\text{R}} = 1 \text{ V}$	-	0.6	Ω
C _d	diode capacitance	$V_R = 1 V$; f = 1 MHz; see Figs 2 and 4	6.4	7.2	pF
		$V_R = 4 V$; f = 1 MHz; see Figs 2 and 4	2.55	2.95	pF
$\frac{C_{d(1V)}}{C_{d(4V)}}$	capacitance ratio	f = 1 MHz	2.2	-	

BB145B

GRAPHICAL DATA







PACKAGE OUTLINE

Plastic surface-mounted package; 2 leads



BB145B

SOD523

BB145B

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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BB145B

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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